

L Number	Hits	Search Text	DB	Time stamp
4	2657096	wafer wafers substrate substrates semiconductor semiconductors	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:35
5	180482	polish polishing planarize planarizing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:35
6	1134973	carrier carriers	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:36
7	87	(membrane membranes) with chambers with concentric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:36
8	3	(wafer wafers substrate substrates semiconductor semiconductors) same (polish polishing planarize planarizing) same (carrier carriers) same ((membrane membranes) with chambers with concentric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:39
9	3	(wafer wafers substrate substrates semiconductor semiconductors) same (carrier carriers) same ((membrane membranes) with chambers with concentric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:44
12	22	independently near3 controlable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:45
13	0	(carrier carriers) with ((membrane membranes) with chambers with concentric) with (independently near3 controlable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:49
14	49	"0115397"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:49
15	7972	kajiwara.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:50
16	0	"0115397" and kajiwara.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 10:50
17	19	kajiwara.in. and subcarrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 11:21
18	30519	retaining adj ring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 11:21
19	1111692	bearing bearings	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 11:21

20	3476	(retaining adj ring) with (bearing bearings)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 11:22
21	436	((retaining adj ring) with (bearing bearings)) and (carrier carriers)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 11:22
22	1		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 11:22
23	1932	(retaining adj ring) near5 (bearing bearings)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 11:28
24	247	((retaining adj ring) near5 (bearing bearings)) and (carrier carriers)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 11:23
25	31	((retaining adj ring) near5 (bearing bearings)) with (carrier carriers)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 11:23
26	108	((retaining adj ring) near5 (bearing bearings)) and (wafer wafers substrate substrates semiconductor semiconductors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 12:04
27	2610	hydrostatic adj bearing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 12:04
28	2610	(bearing bearings) and (hydrostatic adj bearing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 12:05
29	82208	(roller ball fluid) adj bearing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 12:05
30	456	(hydrostatic adj bearing) and ((roller ball fluid) adj bearing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 12:05
31	27	((hydrostatic adj bearing) and ((roller ball fluid) adj bearing)) and (polish polishing planarize planarizing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/06 12:05